SLIP 2006 in Munich, Germany

Modeling and Analysis of the System Bus on the SoC Platform

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- **SoC** platform & shared-bus
- Design issue
- Proposed latency model
- **Simulation & result**
- **Conclusions**

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SoC platform & shared-bus

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Platform based SoC design



Shared bus for interconnection

- Simple architecture
- Totally reusable
- Lower speed than resident cores
- Performance depends on an arbitration
- Efficient solution in the current design flows

Single-layer bus

- Number of IPs on a bus
- Only one master grabs a ownership at a time



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Multi-layer bus

Multi-path between master and slave

- Each layer can be simple
- Increase bandwidth

🗊 Weak point

- Hardware resource
- Power
- Design complexity



AMBA: popular standard for SoC

Open standard, on-chip bus specification by ARM

- 🗇 AHB, ASB, APB, AXI
- Support multi-layer architecture
- Advanced High-performance Bus
 - Pipelined operation
 - Non-tristate implementation
 - Multiple bus masters
 - Burst transfers
 - Split transactions



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Design issue

How can you estimate a throughput from the present shared-bus before actual design?

- Number of masters
- Number of layers
- Transfer properties

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IS(Ideal-Slave) latency model

- A slave has no latency to response to a master.
- L_{Bus} Latency of shared-bus
- L_{Complex_Bus} Latency of shared-bus including multiple master
- L_{Single_Layer} Latency of single-layer bus
- L_{Multi_Layer} Latency of multi-layer bus

Parameter	Description
N _M	Number of masters
NL	Number of layers
N _D	Number of data
S	Single transfer ratio
В	Burst size
U	Usage of bus
A	Active bridge ratio

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Modeling (1/8)

Latency for shared bus

Clock $L_{\text{Bus}} = 1 + N_D$ (1) IDLE Master A IDLE IDLE ,where N_{D} is number of data and Request '1' indicate the request cycle Address getting approval from a bus arbiter Data (a) Single transfer Consider an effect of transfer mode and pipelined architecture Clock IDLE Master A Master A Master A $L_{\text{Bus}} = 3 \cdot N_D \cdot S$ Request (2) + $\left\{ Ceiling\left(\frac{N_D \cdot (1-S)}{B}\right) + N_D \cdot (1-S) \right\}$ Address 1 Address 2 Address 3 Data 1 Data 2 ,where $S(0 \le S \le 1)$ is a ratio of single transfer (b) Burst transfer and B is a burst data size

<An example of two transfer type in shared bus>

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Modeling (2/8)

Latency for single-layer shared bus

$$L_{\text{Single}_Layer} = N_{\text{M}} \cdot L_{\text{Bus}}$$
 (3)

,where N_M is number of masters



<The general single-layer structure>

- All master lps are connected to the single layer bus and are controlled by an arbiter
- This one master IP latency occupies the shared bus

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Modeling (3/8)

Latency for single-layer shared bus



- If two or more master lps are connected to the bus, address and data cycle access the bus simultaneously.
- the effect of the pipeline architecture depends on the bus usage

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Modeling (4/8)

A partition of bandwidth according to number of masters



- lincrease in bus usage means increase the probability of the continuing data processing.

- Total bandwidth is equal to total bandwidth of each master IP.

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Modeling (4/8)

Latency for multi-layer shared bus

$$L_{\text{Multi_Layer}} = \frac{N_M}{N_L} \cdot L_{\text{Bus_Complex}} \cdot (1 - A) + \alpha \cdot A \quad (5)$$

,where A($0 \le U \le 1$) is a probability making a data path through a bridge module. Bridge factor, α , is latency overhead caused by bridge module. N₁ is number of layers.



<The multi-layer structure with bridge module>

Modeling (5/7)

Latency for multi-layer shared bus

-The latency is increased due to bridge modules.

-If two layers are connected through a bridge module, one IP should be a master of both layers.

-It cannot offer entire bandwidth of two layers.



<The configuration of data path with 3-layer bus>

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Modeling (6/7)

Latency for multi-layer shared bus



<The distribution of probability A by combination of data path>

-Bridge factor is the latency overhead by the using bridge.

-Bridge factor depends on the number of data path.

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Modeling (7/7)

Throughtput ratio of multi-layers to single-layer



- the throughput is inversely proportional to A and proprtional to number of layer

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Simulation & Result (1/9)

Result of latency model for shared bus ($N_D = 1000$)

```
-Case1) If same U (bus usage), S 1, latency 1.
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-Case2) If same S (single transfer rate), U \uparrow , latency \downarrow .

If the system which has high U, it doesn't have to much consider about S.



<The variation of latency according to increase of bus usage and single transfer> 22/33

Simulation & Result (2/9)

Result of latency model for shared bus

-The latency is reduced when compare multi-layers with single-layer. (2-layers $45\%\downarrow$, 3-layers $63\%\downarrow$)

-The condition (S, B, U, A) depends on characteristic of SoC.



<The latency difference of each shared bus by parameter number of master IPs> 23/33

Simulation & Result (3/9)

Result of latency model for multi-layer bus

Condition: VGA(640x480), 30frame/s Job requirement: 27.65[MB/s] = 640X480X3[Byte]X30[frame] Total requirement: 110.6[MB/s] = 27.65[MB/s]X4

Maximum throughput of USB2.0 is 480[Mb/s] (= 60[MB/s])



<The simple example of image processing by MPEG>



<The expected throughput of each shared bus according to increase number of masters>

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Simulation & Result (4/9)

We use MaxSim for a comparison of simulation results

- Modeling & simulation tools for SoC designs
- Cycle-accurate models



<The example of SoC on the MaxSim with single-layer and multi-layer>

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Simulation & Result (5/9)

Single-layer results

- N_D = 1000
- 96% accuracy



<The comparison of the results between IS model and MaxSim>

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Simulation & Result (6/9)

2-layer results

- N_D = 1000, A = 20%
- 85% accuracy



<The comparison of the results between IS model and MaxSim>

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Simulation & Result (7/9)

3-layer results

- N_D = 1000, A = 20%
- 85% accuracy

<The comparison of the results between IS model and MaxSim>

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Simulation & Result (8/9)

- The accuracy of the proposed latency model are over <u>96%</u> for single-layer and <u>85%</u> for multiple layers.

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Simulation & Result (9/9)

- The bus usage indicates an average utilization of the bus as function of number of master IPs

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Conclusions

We propose a latency model (IS model) which to estimate a performance of system bus before actual design.

Simulation & result

- Analyze the parameters of shared bus latency
- Analyze number of masters affecting to bus throughput
- Find out an appropriate number of layers on specific SoCs
- Compare the results with that of MaxSim

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Thank you !

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